

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Che-Tung WU	11/20/2007
Chih-Ho HSU	11/20/2007
Kai-Jie TSAO	11/20/2007
RECEIVING PARTY DATA	
Name:	Ichia Technologies, Inc.
Street Address:	268, Hwa-Ya 2nd Road, Hwa-Ya Tech. Park Gueishan
City:	Taoyuan
State/Country:	TAIWAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	11946553
CORRESPONDENCE DATA	
Fax Number: (203)538-4934 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Phone: 5712765506 Email: hdsipr.3@gmail.com Correspondent Name: HDSL Address Line 1: 4331 STEVENS BATTLE LANE Address Line 4: FAIRFAX, VIRGINIA 22033	
ATTORNEY DOCKET NUMBER:	OP-096000664
NAME OF SUBMITTER:	Kao H. Lu
Total Attachments: 1 source=ASS664#page1.tif	

CH \$40.00 11946553

ASSIGNMENT OF APPLICATION FOR UNITED STATES LETTERS PATENT

WHEREAS Che-Tung WU, Chih-Ho HSU and Kai-Jie TSAO
hereinafter referred to collectively as the assignor, has invented a certain improvement relating to

METALLIC PANEL ASSEMBLY HAVING RIPPLE LUSTER

☒ the inventor(s) declaration for said application being executed concurrently with the execution of this instrument; said application to be filed in the United States Patent and Trademark Office;
☐ said application having been filed in the United States Patent and Trademark Office on _____,
(Application Serial No. _____) the application serial number of said application when known;
☐ said application having been filed under the Patent Cooperation Treaty on _____,
(Serial No. _____) the United States of America being designated.

AND WHEREAS Ichia Technologies, Inc.
who's address is 268, Hwa-Ya 2nd Road, Hwa-Ya Tech. Park, Gueishan, Taoyuan, Taiwan, R.O.C.

hereinafter referred to as the assignee, is desirous of acquiring the entire right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefore, including any and all renewals, reissues and prolongations thereof;

NOW THIS WITNESSETH, that for and in consideration of One Dollar (\$1.00), and other good and valuable consideration paid by said assignee to said assignor, the receipt of which is hereby acknowledged, said assignor hereby assigns, sells and transfers to said assignee, and said assignee's successors and assigns, the full and exclusive right, title and interest in and to said application, including any and all divisions and continuations thereof, and in and to said invention and any and all patents which may be granted therefore, including any and all renewals, reissues and prolongations thereof; said assignee, and said assignee's successors and assigns, to have, hold, exercise and enjoy the said application, including any and all divisions and continuations thereof, and the said invention and any and all patents which may be granted therefore, including any and all renewals, reissues and prolongations thereof, with all the rights, powers, privileges and advantages in anywise arising from or appertaining thereto, for and during the term or terms of any and all such patents when granted, including any and all renewals, reissues and prolongations thereof, for the use and benefit of said assignee, and said assignee's successors and assigns, in as ample and beneficial a manner as the said assignor might or could have held and enjoyed the same, if this assignment had not been made.

AND said assignor hereby agrees to perform, upon the request of said assignee, or said assignee's successors or assigns, any and all acts relating to the obtaining or to the asserting of said patents, including any and all renewals, reissues and prolongations thereof.

AND said assignor authorizes and requests the Commissioner of Patents and Trademarks to issue Letters Patent on said application, and on any and all divisions and continuations thereof, to said assignee, and said assignee's successors and assigns, in accordance herewith.

<u>Che-Tung WU</u>	<u>Che - Tung Wu</u>	<u>November 20, 2007</u>
Name of sole or first inventor	Signature	Date

<u>Chih-Ho HSU</u>	<u>Chih - Ho Hsu</u>	<u>November 20, 2007</u>
Name of second inventor, if any	Signature	Date

<u>Kai-Jie TSAO</u>	<u>Kai - Jie Tsao</u>	<u>November 20, 2007</u>
Name of third inventor, if any	Signature	Date

Name of fourth inventor, if any	Signature	Date
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Name of fifth inventor, if any	Signature	Date
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